Specifications

Drawing No.	UKY1C-H1-14E52-00[31] 1/11
Issued Date.	Dec,26,2014

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Note: In case of specification change, KYOCERA Part Number also will be changed.

Product Name	Quartz Crystal
Product Model	CX2520DB
Frequency	38400kHz
Customer Part Number	-
Customer Specification Number	-
KYOCERA Part Number	CX2520DB38400D0FZGC1
Remarks Pb-Free, RoHS Comp	bliant, MSL 1

Customer Acceptance

Accept Signature	Approved Date	
	Department	
	Person in charge	

Seller KYOCERA Crystal Device Corporation

(Sales Division)

6 Takeda Tobadono-cho, Fushimi-ku, Kyoto

612-8501 Japan

TEL. No. 075-604-3500 FAX. No. 075-604-3501

Manufacturer

Crystal Units Division

5850, Higashine-Koh, Higashine-Shi, Yamagata

999-3701 Japan

TEL. No. 0237-43-5611 FAX. No. 0237-43-5615

Design Department	Quality Assurance	Approved by	Checked by	Issued by
KYOCERA Crystal Device Corporation Crystal Units Engineering Section 1 Crystal Units Division	T. Noritake	K. Yamazaki	T. Nitoube	Y. Kikuchi

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Revision History

Rev.No.	Description of revise	Date	Approved by	Checked by	Issued by
1	First Edition	Dec,26,2014	K. Yamazaki	T. Nitoube	Y. Kikuchi

1. APPLICATION

This specification sheet is applied to quartz crystal "CX2520DB38400D0FZGC1"

2. KYOCERA PART NUMBER

CX2520DB38400D0FZGC1

3. RATINGS

Items	SYMB.	Rating	Unit	Remarks
Operating Temperature	Topr	-25 to +85	°C	
Storage Temperature range	Tstg	-40 to +85	°C	

4. CHARACTERISTICS ELECTRICAL CHARACTERISTICS

Items		Electrical Specification				Test Condition	Remarks
	SYMB.	Min	Тур.	Max	Unit		
Mode of Vibration		F	undament	al			
Nominal Frequency	F0		38.4		MHz		
Nominal Temperature	T _{NOM}		+25		°C		
Load Capacitance	CL		8.0	1	pF		
Frequency Tolerance	df/F	-10.0		+10.0		+25±3°C	
Frequency	df/F	-11.0		+11.0		-25 to +85°C	
Temperature		-11.0		+5.0		-20°C	
characteristics		-3.0		+9.0	PPM	-10°C	
		-11.0		+1.0		+65°C	
		-7.0		+11.0		+85°C	
Frequency Aging Rate		-1.0		+1.0		1 st year	+25±3°C
Equivalent Series Resistance	ESR			80	Ω		
Shunt Capacitance	C0			2.0	pF		
Pull ability			-24.2		ppm/pF		
Drive Level	Pd	0.01		10	μW		
Insulation Resistance	IR	500			ΜΩ	100V(DC)	

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5. Measurement Condition

5.1 Frequency measurement

Measuring instrument : IEC PI-Network Test Fixture

Load Capacitance : 8.0pF Drive Level : 10µW

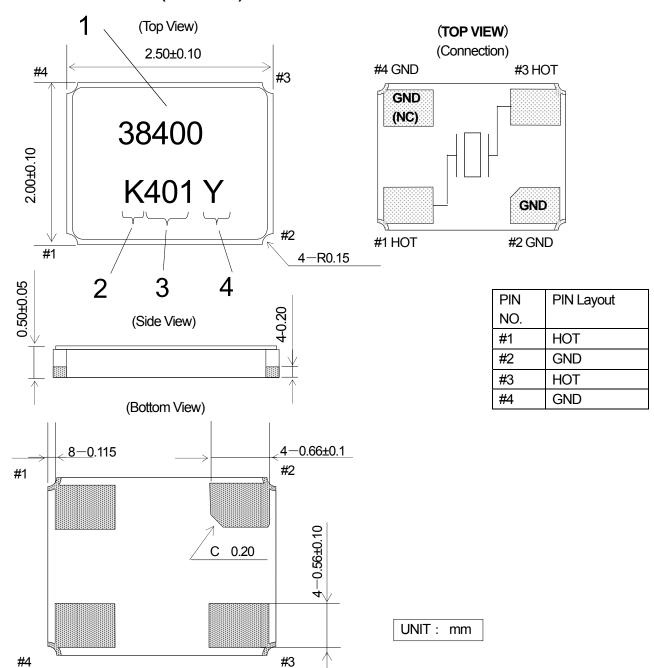
5.2 Equivalent series resistance (ESR) measurement

Measuring instrument : IEC PI-Network Test Fixture

Load Capacitance : Series
Drive Level : 10µW

Drawing No.

6. APPEARANCES, PHYSICAL DIMENSION OUTLINE DIMENSION (not to scale)



MARKING

- 1 Nominal Frequency Move the number of maximum indication beams of the frequency to five digits, and omit less than kHz.
- 2 Identification [K] mark is surely 1Pin direction.
- 3 Date Code Year…LAST 1 DIGIT of YEAR AND WEEK

(Ex)Jan,01, 2014 \rightarrow 401

4 Manufacturing Location

Y···Japan(Yamagata)

Z···Japan(Shiga Yohkaichi)

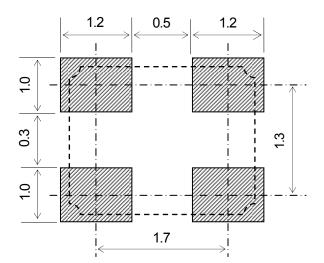
T···Thailand

F...Philippines

%The font of marking is reference.

KYOCERA Crystal Device Corporation

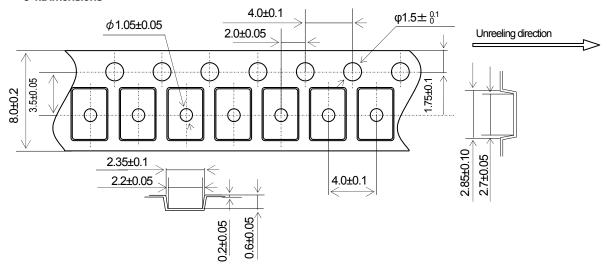
7. RECOMMENDED LAND PATTERN (not to scale)



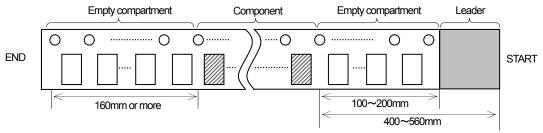
UNIT: mm

8. TAPING&REEL

8-1.Dimensions



8-2.Leader and trailer tape

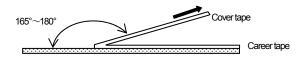


8-3.Direction (The direction shall be seen from the top cover tape side)

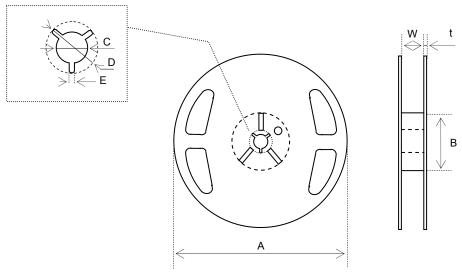


8-4. Specification

- 1. Material of the carrier tape is either polystyrene or A-PET (ESD).
- 2. Material of the cover tape is polyester (ESD).
- 3. The seal tape shall not cover the sprocket holes and not protrude from the carrier tape.
- 4. Tensile strength of carrier tape: 10N or more.
- 5. The R of the corner of each cavity is 0.2RMAX.
- 6. The alignment between centers of the cavity and sprocket hole shall be 0.05mm or less.
- 7. The orientation shall be checked from the top cover tape side as shown in 8-3.
- 8. Peeling force of cover tape: 0.1 to 1.0N.
- 9. The component will fall out naturally when cover tape is removed and set upside down.



8-5.Reel Specification



φ180 Reel (3,000 pcs)

Symbol	А	В	С	D
Dimension	φ180 +0/-3	φ60 +1/-0	φ13±0.2	φ21±0.8
Symbol	E	W	t	
Dimension	2.0±0.5	9±1	2.0±0.5	

(Unit: mm)

3000pcs taping Only

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9. Enviromental requirements

After conducting the following tests, component needs to meet below conditions.

Frequency: Fluctuation within +/-10 x 10⁻⁶

CI: Fluctuation within $\pm -20\%$ or ± 50 whichever is larger

9.1 Resistance to Shock Test condition

3 times natural drop from 100cm onto hard wooden board.

9.2 Resistance to Vibration Test condition

frequency : 10 - 55 - 10 Hz

Amplitude : 1.5mm

Cycle time : 15 minutes

Direction : X,Y,Z (3direction),2h each.

9.3 Resistance to Heat Test condition

The quartz crystal unit shall be stored at a

temperature of +85 \pm 2°C for 500h and subjected to room temperature for 1h before measurement.

9.4 Resistance to Cold Test condition

The quartz crystal unit shall be stored at a

temperature of $-40\pm2^{\circ}$ C for 500h and subjected to room temperature for 1h before measurement.

9.5 Thermal Shock Test condition

The quartz crystal unit shall be subjected to 500 temperature cycles shown in table below, Then it shall be subjected

to room temperature for 1h before mesurement.

Cycle : $-40\pm2^{\circ}$ C (30min.) \rightarrow +25 $\pm2^{\circ}$ C (5min.) \rightarrow +85 $\pm2^{\circ}$ C (30min.) \rightarrow +25 $\pm2^{\circ}$ C (5min.)

9.6 Resistance to Moisture

Test condition

The quartz crystal unit shall be stored at a temperature of +60 \pm 2°C with relative humidity of 90% to 95% for 240 h. Then it shall be subjected to room temperature for 1h before measurement.

9.7 Soldering condition

1.) Type of solder

Material ··· lead free solder paste

Melting point \cdots +220 \pm 5°C

2.) Reflow temp.profile

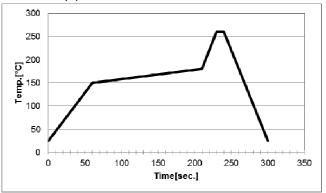
	Temp [°C]	Time[sec]
Preheating	+150 to +180	150 (typ.)
Peak	+260±5	10 (max.)
Total	_	300 (max.)

Frequency shift : ±2ppm

3.) Hand Soldering +350°C 3 sec max

4.) Reflow Times 2 times in below Reflow temp. profile

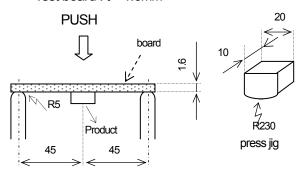
Reflow temp.profile



9.8 Bending Strength

Solder this product in center of the circuit board ($40 \text{mm} \times 100 \text{mm}$), and add deflection of 3mm.

Test board: t=1.6mm



UNIT: mm

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10. Cautions for use

(1) Soldering upon mounting

There is a possibility to influence product characteristics when Solder paste or conductive glue comes in contact with product lid or surface.

(2) When using mounting machine

Please minimize the shock when using mounting machine to avoid any excess stress to the product.

(3) Conformity of a circuit

We strongly recommend to make sure that Negative resistance (Gain) of IC is designed to be 5 times the ESR (Equivalent Series Resistance) of crystal unit.

11. Storage conditions

Please store product in below conditions, and use within 6 months.

Temperature +18 to +30°C, and Humidity of 20 to 70 % in the packaging condition.

12. Manufacturing location

Kyocera Crystal Device Corporation Yamagata Plant

Kyocera Crystal Device Corporation Shiga Yohkaichi Plant

Kyocera Crystal Device (Thailand) Co., Ltd

Kyocera Crystal Device Philippines, Inc.

13. Quality Assurance

To be guaranteed by Kyocera Crystal Device Quality Assurance Division

14. Quality guarantee

In case when Kyocera Crystal Device Corporation rooted failure occurred within 1 year after its delivery, substitute product will be arranged based on discussion. Quality guarantee of product after 1 year of its delivery is waivered.

15. Others

In case of any questions or opinions regarding the Specification, please have it in written manner within 45 days after issued date.